

ABSTRACT OF THE DISCLOSURE

An upper mold, a lower mold, a middle mold, and a release film are used in a method of resin sealing of an electronic component. The release film is sandwiched between the lower mold and the middle mold and held under a prescribed tension to cover a cavity of the lower mold. A cavity side surface is also covered with the release film. Therefore, releasability of a cured resin from the cavity side surface is increased. As a result, the cured resin is prevented from being damaged near the cavity side surface.